

L Number	Hits	Search Text	DB	Time stamp
1	18	(((((adder or subtractor) and comparator) and chip and package) and memory ) and juxtaposed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/25 10:11
2	13	((((identify or identifying or identifier).ab. and (identify or identifying or identifier).clm. and memory.ab. and memory.clm. and (adder or subtractor).ti,ab,clm. ) and (memory near10 (identify or identifying or identifier)).ab.) and (memory near10 (identify or identifying or identifier)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/25 10:11
3	23	(memory near5 (identifier or identifying)).clm. and (memory near5 (identifier or identifying)).ab. and sdram	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/25 10:11
4	2	(((((memory.ti,ab,clm. and identifier.ti,ab,clm. and (stack or stacking or stacked).ti,ab,clm.) and identifier.clm.) and memory.clm.) and (stack or stacked or stacking).clm.) and (memory near10 (bond or bonded or bonding or mount or mounting or mounted)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/25 10:11
5	16	(memory near10 (stack or stacked or stacking) near10 (module or chip or ic or semiconductor)).ti,ab,clm. and (identifying or identifier).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/25 10:12
6	10	((memory near5 identifier).clm. and (memory near5 (identifier or identifying)).ab.) and (memory near4 (stack or stacked or stacking))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/25 10:12
7	10	((((identify or identifying or identified or identifier) near10 (memory or storage or ic or chip or semiconductor)).clm. and ((select or selecting or selected or selector) near10 (memory or storage or ic or chip or semiconductor)).clm.) and ((identify or identifying or identified or identifier) near10 (adder or subtractor)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/25 10:12

8	76	(((identify or identifying r identifier or id ntified) near10 (memory or dram or ram or storag ) n ar10 (select or s lected or selecting) near10 (unit or module or ic or chip or cell)) and (identify or identifying or identifier or identified).ti,ab,clm. and (memory or storage or ram or dram).ti,ab,clm. ) and identifier.clm.) and identifier.ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/25 10:12
9	3	(select or selecting) near memory near (unit or module or ic or chip or semiconductor).clm. and (identify or identifying or identifier).clm. and (dram or sdram)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/25 10:12

<b>L Number</b>	<b>Hits</b>	<b>S arch Text</b>	<b>DB</b>	<b>Time stamp</b>
-	1	"m mory unit" and (decode or decoded or decoding or decoder) and "identifying unit" and "sense amplifier"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 12:59
-	76	"memory unit" and "identifying unit"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 12:59
-	1	(( "memory unit" and "identifying unit" ) and signal and (select or selecting or selected)) and (adder or subtracter)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 13:01
-	40	("memory unit" and "identifying unit" ) and signal and (select or selecting or selected)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 13:02
-	5218	(adder or subtracter) and comparator and memory and (dram or sram or eprom or rom or eeprom)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 13:04
-	816	((adder or subtracter) and comparator and memory and (dram or sram or eprom or rom or eeprom)) and (stack or stacking or stacked)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 13:04
-	790	((((adder or subtracter) and comparator and memory and (dram or sram or eprom or rom or eeprom)) and (stack or stacking or stacked)) and (select or selected or selecting) and bit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 13:05
-	48	(((((adder or subtracter) and comparator and memory and (dram or sram or eprom or rom or eeprom)) and (stack or stacking or stacked)) and (select or selected or selecting) and bit) and register and counter and "clock buffer"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 13:06
-	48	(((((adder or subtracter) and comparator and memory and (dram or sram or eprom or rom or eeprom)) and (stack or stacking or stacked)) and (select r s lected or sel cting) and bit) and r gister and counter and ("clock buffer" or "clk buffer")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 13:06

-	52	(((adder or subtract r) and comparat r and mem ry and (dram or sram or eprom r rom or e pr m)) and (stack or stacking or stacked)) and (select or selected or selecting) and bit) and register and counter and ((clock or clk) near buffer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/06 14:26
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L Number	Hits	S arch Text	DB	Tim stamp
-	6	((memory adj (modul or chip or ic r semiconductor or unit)) same (select or selecting or selected or selector) same signal same terminal same (identifying or identifier or identify or identified)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:06
-	244	((memory adj (module or chip or ic or semiconductor or unit)) same (select or selecting or selected or selector) same (identifying or identifier or identify or identified)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:07
-	39	((memory adj (module or chip or ic or semiconductor or unit)) same (select or selecting or selected or selector) same (identifying or identifier or identify or identified)).ti,ab,clm.) and identifier.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:08
-	6	(identifier near10 memory).ti,ab,clm. and ((adder or subtracter) near10 identifier).ti,ab,clm. and ((storage or dram or sdram or memory) near3 (unit or module or ic or chip or semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:11
-	7	((memory near5 (stacking or stacked or multichip or multilayer or multilevel or multi-chip or multi-layer or multi-level or dimensional)).ti,ab,clm. and identifier.ti,ab,clm.) and (dram or sdram or sram)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:13
-	56	(memory near5 (stacking or stacked or multichip or multilayer or multilevel or multi-chip or multi-layer or multi-level or dimensional)).ti,ab,clm. and identifier.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:14
-	251	(bond or bonding or bonded or mount or mounted or mounting) and (dram or sdram or sram) and identifier.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:17
-	1	((bond or bonding or bonded or mount or mounted or mounting) near10 (dram or sdram or sram or memory or prom or eprom or eeprom or nonvolatile or non-volatile)) and (identifier near10 (adder or subtracter)) and identifier.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:20
-	11	((b nd or bonding or bonded or mount or mounted or mounting) near10 (dram or sdram r sram or mem ry or pr m or eprom r eeprom or nonvolatil or non-v latile)) and (identifier and (adder r subtract r)) and identifier.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:22

-	451	((bond or bonding or bonded or mount or mounted or mounting) near10 (dram or sdram or sram or memory or prom or eeprom or nonvolatile or non-volatile)) and (identifying or identifier).ti,ab,clm. and (stacked or stacking or laid or multichip or multilayer or multilevel or multi-chip or multi-layer or multi-level or dimensional))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:24
-	90	((bond or bonding or bonded or mount or mounted or mounting) near10 (dram or sdram or sram or memory or prom or eeprom or nonvolatile or non-volatile)) and (identifying or identifier).ti,ab,clm. and (stacked or stacking or laid or multichip or multilayer or multilevel or multi-chip or multi-layer or multi-level or dimensional)) and identifier.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:24
-	17	((bond or bonding or bonded or mount or mounted or mounting) near10 (dram or sdram or sram or memory or prom or eeprom or nonvolatile or non-volatile)) and (identifying or identifier).ti,ab,clm. and (stacked or stacking or laid or multichip or multilayer or multilevel or multi-chip or multi-layer or multi-level or dimensional)) and identifier.clm.) and (identifier or identifying).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:26
-	19	((bond or bonding or bonded or mount or mounted or mounting) near10 (dram or sdram or sram or memory or prom or eeprom or nonvolatile or non-volatile)) and (identifying or identifier).ti,ab,clm. and (stacked or stacking or laid or multichip or multilayer or multilevel or multi-chip or multi-layer or multi-level or dimensional)) and identifier.clm.) and (select or selecting or selected or selector).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:26
-	47	((bond or bonding or bonded or mount or mounted or mounting) near10 (dram or sdram or sram or memory or prom or eeprom or nonvolatile or non-volatile)) and (identifying or identifier).ti,ab,clm. and (stacked or stacking or laid or multichip or multilayer or multilevel or multi-chip or multi-layer or multi-level or dimensional)) and identifier.clm.) and (select or selecting or selected or selector).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:26

-	6	<p> ((((bond or bonding or bonded r mount or m unted or mounting) near10 (dram or sdram or sram r memory or prom or epr m or eeprom or nonvolatile or non-volatile)) and (identifying or identifier).ti,ab,clm. and (stacked or stacking or laid or multichip or multilayer or multilevel or multi-chip or multi-layer or multi-level or dimensional)) and identifier.clm.) and (select or selecting or selected or selector).clm.) and (identifier or identifying).ab. </p>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/13 09:26
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